



May 27, 2021 – Webinar

Hybrid wafer-scale and die-level integration in microfluidics

packaging and integration of micro/nanostructures, sensors or other microdevices

Advanced Wafer-Level Processes for Next-Gen Integrated Microfluidics

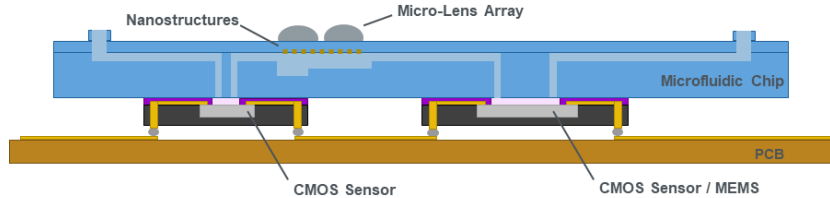
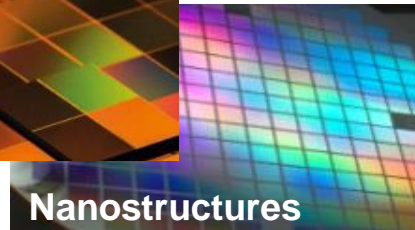
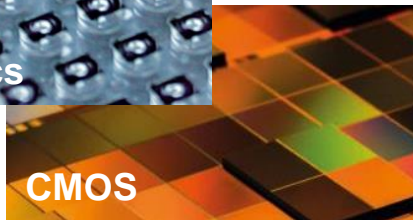
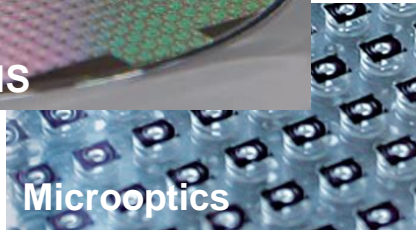
Dr. Bernd Dielacher

Business Development Manager

Advanced Wafer-Level Processes for Next-Gen Integrated Microfluidics



Enabling Next-Generation Bio- and Medical Devices through Proven Leading-Edge Semiconductor Process Solutions and Expertise



- Enabling high resolution ordered nanopatterns in microfluidics
- Cost-efficient silicon-microfluidic integration
- Ultrathin adhesive bonding at room-temperature